



1EW 1753  
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Docket No.: 50352-020

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
Shiroshi MATSUKI, et al.	:	Confirmation Number: 9915
Serial No.: 09/944,344	:	Group Art Unit: 1753
Filed: September 04, 2001	:	Examiner: Edna Wong

For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR  
MANUFACTURING SAME AND COPPER ELECTROPLATING METHOD

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated December 11, 2004, please amend the  
application as follows: